

US/900130
11/11/97
250
Class
Subclass
ISSUE CLASSIFICATION
SCANNED

UTILITY SERIAL NUMBER	PATENT DATE SEP 14 1999	PATENT NUMBER
SERIAL NUMBER	FILING DATE	CLASS
		SUBCLASS
		GROUP ART UNIT
		EXAMINER

5952646
5952646

APPLICANTS

None

yes United Kingdom 96269725 Dec. 27, 1996

Foreign priority claimed 35 USC 119 conditions met	<input checked="" type="checkbox"/> yes <input type="checkbox"/> no	AS FILED	STATE OR COUNTRY	SHEETS DRWGS.	TOTAL CLAIMS	INDEP. CLAIMS	FILING FEE RECEIVED	ATTORNEY'S DOCKET NO.
Verified and Acknowledged	Examiners Initials							

ADDRESS

Low Temperature Bump-Bonding Semiconductor Imaging Device

TITLE

U.S. DEPT. OF COMM./PAT. & TM--PTO-436L (Rev.12-94)

PARTS OF APPLICATION FILED SEPARATELY		4/14/99 Applications Examiner	
NOTICE OF ALLOWANCE MAILED		CLAIMS ALLOWED	
24-9-99		Total Claims 30	Print Claim 1
ISSUE FEE		DRAWING	
Amount Due 6005.00	Date Paid 6/10/99	Sheets-Drwg. 3	Figs. Drwg. 6
Label Area		Print Fig. 2	ISSUE BATCH NUMBER R57
PREPARED FOR ISSUE			
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Form PTO-436A
(Rev. 8/97)
SCAN 8 CB
Formal Drawings (ents) \$61
QC/MC
DWG

ISSUE FEE IN FILE
(FACE)